

ABSTRACT

MULTI-LAYER DOUBLE-SIDED WIRING BOARD AND METHOD OF FABRICATING THE SAME

Disclosed herein are multi-layer double-sided wiring boards having an insulating layer with an opening, conductive layers on both surfaces of the insulating layer and on the inside of the opening, and an interface layer between the insulating layer and portions of the conductive layers wherein the conductive layers are in direct contact in the opening. Also disclosed are methods of fabricating such multi-layer double-sided wiring boards.